



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC046N10NS3 G		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA002434898						
<b>Package</b>		PG-TDSON-8-7		<b>Weight*</b>		119.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.818	1.52	1.52	15190	15190
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		316	
wire	non noble metal	copper	7440-50-8	37.762	31.54	31.58	315440	315851
	noble metal	gold	7440-57-5	0.044	0.04	0.04	371	371
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		706	
	plastics	epoxy resin	-	6.679	5.58		55794	
leadfinish	inorganic material	silicondioxide	60676-86-0	35.509	29.66	35.31	296626	353126
	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12126	12126
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1383	1383
solder	non noble metal	tin	7440-31-5	0.050	0.04		416	
	noble metal	silver	7440-22-4	0.062	0.05		520	
heatspreader	non noble metal	lead	7439-92-1	2.380	1.99	2.08	19879	20815
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
heat sink CLIP	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.46	9.47	94561	94684
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		186	
*deviation	non noble metal	copper	7440-50-8	22.292	18.62	18.65	186212	186454
	< 10%				Sum in total:		100.00	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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